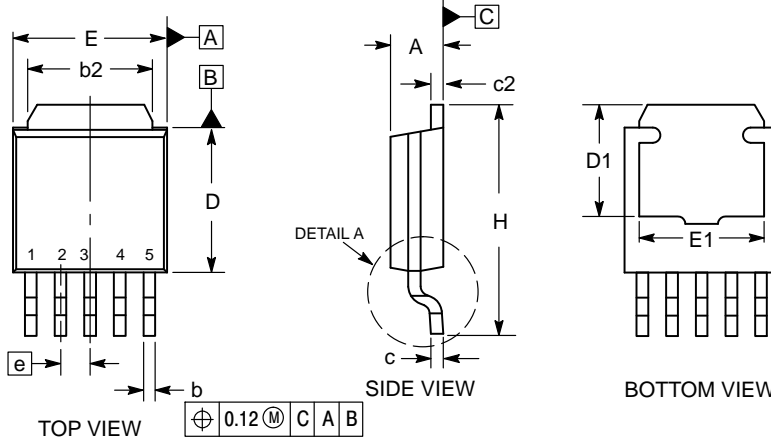


DPAK i5 (TO i252, 5 LEAD)
CASE 369AE
ISSUE A

DATE 14 AUG 2013

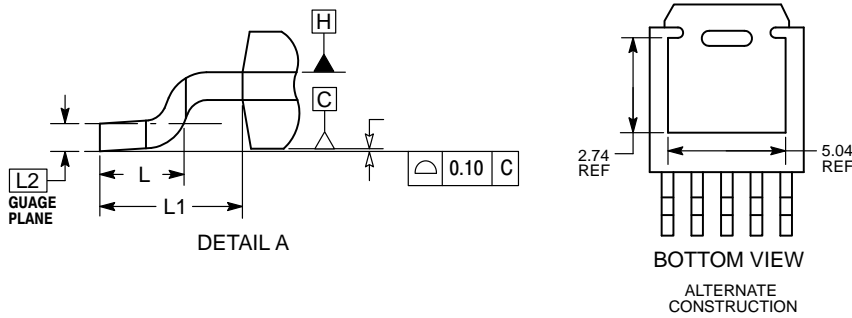
SCALE 1:1



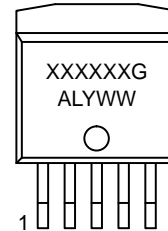
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL, WITHIN DIMENSIONS SHOWN.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	MILLIMETERS	
	MIN	MAX
A	2.10	2.50
A1	0.00	0.13
b	0.40	0.60
b2	5.14	5.54
c	0.40	0.60
c2	0.40	0.60
D	5.40	6.30
D1	4.80	5.10
E	6.35	6.80
E1	4.75	5.05
e	1.27 BSC	
H	9.50	10.20
L	1.39	1.78
L1	2.50	2.90
L2	0.51 BSC	

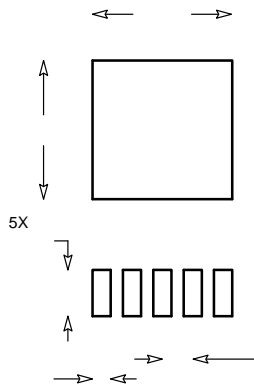


GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb iFree Package

*This information is generic. Please refer to device data sheet for actual part marking.



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DESCRIPTION:	DPAK i5 (TO i252, 5 LEAD)	PAGE 1 OF 1

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